

Customer No.: 31561
Application No.: 10/709,954
Docket NO.: 11530-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

1. (original) An electrical package comprising:

a multi-layer interconnection structure having a top surface, a bottom surface and an inner circuit therein, wherein the inner circuit has a plurality of bonding pads on the bottom surface of the multi-layer interconnection structure;

at least an electronic device positioned on the top surface of the multi-layer interconnection structure and electrically connected to the inner circuit of the multi-layer interconnection structure; and

a support substrate made from a conductive material, wherein the support substrate is positioned on the bottom surface of the multi-layer interconnection structure, and the support substrate has a plurality of first openings that exposes one of the corresponding bonding pads.

2. (original) The electrical package of claim 1, wherein the package further comprises an isolation layer made from an insulation material such that the isolation layer is disposed between the multi-layer interconnection structure and the support substrate and that the isolation layer has a plurality of second openings that exposes one of the corresponding bonding pads.

3. (original) The electrical package of claim 1, wherein each bonding pad has a barrier layer thereon such that the barrier layer is exposed by the first opening.

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4. (original) The electrical package of claim 1, wherein the electronic device comprises a die, a passive component or an electrical package.
5. (original) The electrical package of claim 1, wherein material constituting the support substrate comprises a metallic material or an alloy.
6. (original) The electrical package of claim 1, wherein the package further comprises a plurality of contacts connected to various bonding pads through corresponding first openings.
7. (original) The electrical package of claim 6, wherein the contacts are configured as solder balls, pins or electrode blocks.
8. (original) The electrical package of claim 6, wherein at least one of the contacts completely fills the first opening so that the contact is electrically connected to the support substrate.
9. (original) The electrical package of claim 1, wherein the package further comprises at least an insulation layer disposed over a sidewall of at least one of the first openings.
10. (original) The electrical package of claim 1, the package further comprises a solder mask layer disposed over a sidewall of at least one of the first openings.
11. (original) The electrical package of claim 1, wherein the electronic device is electrically connected to the inner circuit within the multi-layer interconnection structure through flip-chip bonding, wire-bonding or a thermal pressure bonding.

Claims 12-30 (canceled)